



IEEE SW Test Workshop

Semiconductor Wafer Test Workshop

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Can testers and probe cards keep up with speed requirements for image sensors?



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Abstract

The MIPI alliance has been defining standards for serial interfaces.

D-PHY, which was ratified 1.5 years ago supports 1Gbps per lane. The M-PHY specification, whose 1.0 version is about to be ratified, supports about 1.25Gbps/1.5Gbps and has options to support 2.5Gbps/3Gbps and 5Gbps/6Gbps per lane.

Per Cosmic Circuits, one of the most successful usage of the DPHY has been in the Camera to Application Processor (CSI) and Application processor to Display (DSI) pipes. D-PHY is a source synchronous system requiring transmission of a clock along with the data. As the bandwidth requirement increases, multiple D-PHY lanes would be required which increases the system cost. This problem has been addressed by the MIPI alliance through the M-PHY. The M-PHY has been defined as an asynchronous system with the clock embedded in the data stream itself. A 3Gbps M-PHY sub-link requires only 2 signals (1 Data lane) while an equivalent D-PHY system would have required 4 times the number of signals (3 Data lanes + 1 Clock lane) resulting in lower power and cost for data transmission.. The M-PHY further defines higher data rates scaling to 6Gbps for future applications.

We have recently received inquiries for high parallelism probe cards capable of supporting 1.5 Gbps speeds. Working in conjunction with Advantest we have actually been able to achieve speeds of 2.5Gbps.

This presentation will discuss the challenges and solutions of meeting the increasingly greater need for speed from the perspective of a tester and probe card supplier.

Contents

- High speed driver
- Terms/ Definitions
- Standards
- Requirements
- Tester interconnection and Loss
- Probe card interconnection and Loss of 1.3Gbps/3Gbps designs
 - Probe Head
 - Probe card board
- Follow on works

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High Speed Drivers

Nokia Lumia Icon
20 MP camera



LG G2
12 MP camera



Samsung Galaxy 4S
16 MP camera



Samsung has put everything it knows about HDTV on brilliant display with the 5.1-inch Full HD Super AMOLED® screen on the Galaxy S5. Movies come to life as they were meant to be seen

Capture Stunning Video
in 1080p HD

The large 5.2" Full HD 1080p IPS display offers the superior clarity of 423-pixel-per-inch resolution to deliver extraordinary graphics and sharp text, all with the beauty of true-to-life colors.
16:9 high-definition

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More Data Drives Need for Higher Speed

- **Display resolution increasing for video and still**
 - 1080P
 - In July 2008, the ATSC standards were amended to include [H.264/MPEG-4 AVC](#) compression and 1080p at 50, 59.94 and 60 frames per second (**1080p50** and **1080p60**). Source: wikipedia
- **More Megapixels in cameras**
- **Need to take multiple pictures to get one good high resolution picture**

Terms/ Definitions

- **Frame rate: Number of still images that make up one second's worth of video or animation**
 - Frames per second "[fps](#)", is a measure of frame rate
 - The higher the frames per second value, the smoother the video (or animation) will appear
 - 30fps or faster is typical for smooth video, while 15fps or lower will have noticeable flicker or choppiness.
- **Bit rate: Number of bits processed/sec**
 - 1 Gbit/s (one gigabit or one billion bits per second) = 1,000,000,000 bit/s rate
- **D PHY – MIPI Alliance Standard for interface**
- **M PHY- MIPI Alliance Standard for interface**

MIPI Alliance Standards

Overview of D-PHY and M-PHY

Min. number of pins per direction		4	2
Minimum configuration		4 pins half-duplex	4 pins dual-simplex
Minimal UniPRO configuration		8 pins	4 pins
Medium		< 30 cm PCB, flex, micro coax	< 30 cm PCB, flex, micro coax, > 5 m optical
Data rate per lane	HS	> 80 Mb/s (Practical limit <1Gb/s)	~ 1.25 , 2.5 , 5 Gb/s ~ 1.5 , 3 , 6 Gb/s 10k-600Mb/s
	LP	< 10 Mb/s	
Electrical signaling	HS	SLVS-200	SLVS-120
	LP	LVC MOS1.2V	SLVS-200 w/o RX-R _T
HS Clocking method		DDR Source-Sync Clk	Custom Clk
HS Line coding		None or 8b9b	8b10b
Power – Energy/bit		Low	Lower
Receiver CDR required		No	Yes
Suited for repeater or optical		No	Yes
LP only PHY's		Disallowed	Allowed

D-PHY version 1.2 just released at 2Gbps

MIPI Alliance web site

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Mobile Camera Interface

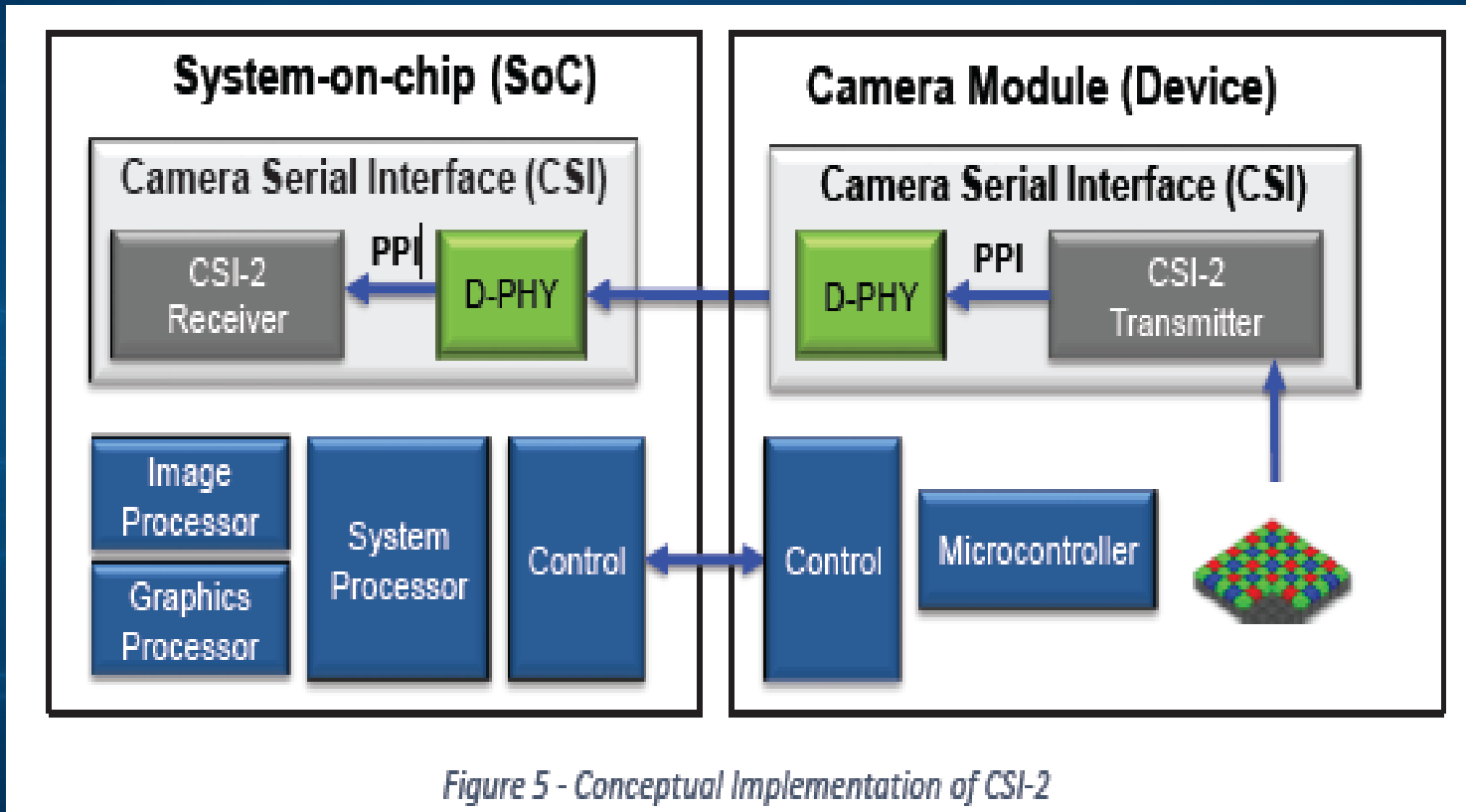


Figure 5 - Conceptual Implementation of CSI-2

source: Arasan Chip Systems, Inc.

Video Camera RAW Bandwidth

	iPhone 4/5	Galaxy S4	RED Epix-X ¹
Camera Image Size Px	1920x1080	3264 x 2448	5120x2700
Mpixel	2.1	8.0	13.8
Gbps @30fps	CSI-2 D-PHY 4 Lanes	CSI-3 M-PHY 4 Lanes	9.95
Gbps @60fps		11.5 (n/a)	19.9
Gbps @120fps		23 (n/a)	38.8

CSI-2 D-PHY 4 Lanes

CSI-3 M-PHY 4 Lanes

unsupported

source: Arasan Chip Systems, Inc.

1 – Professional camera \$20K+

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Display RAW Bandwidth

	iPhone 4/5	iPad 3 / 4	Galaxy S4	4K tablet ¹	8K tablet ²
Display Size Px	960x640	2048x1536	1920x1080	3840x2560	7680x4320
PPI	326	264	441	230	~700
Mpixel	0.6	3.1	2.1	9.8	~32
Gbps @30fps				7.08	23.89
Gbps @60fps				14.16	48
Gbps @120fps		9.06		28	95
Gbps @240fps		18.2	12	57	191

DSI D-PHY 4 Lanes

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DSI-2 M-PHY 4 Lanes

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unsupported

source: Arasan Chip Systems, Inc.

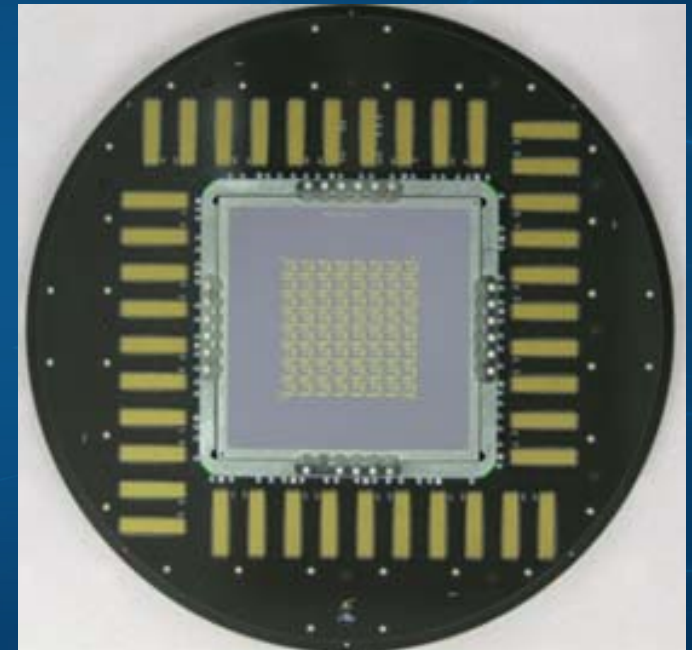
Need for Speed

**Are you convinced that we need
higher speed?**

Systematic Approach Required



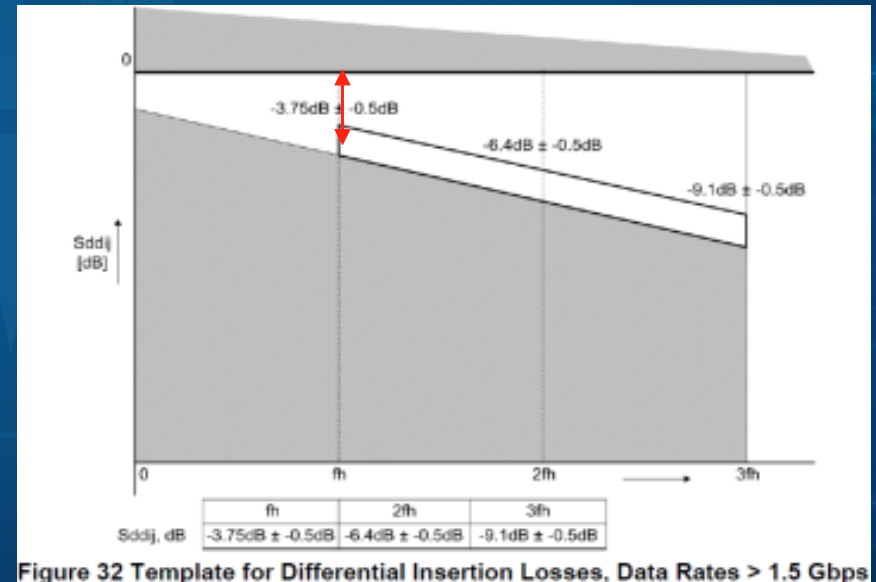
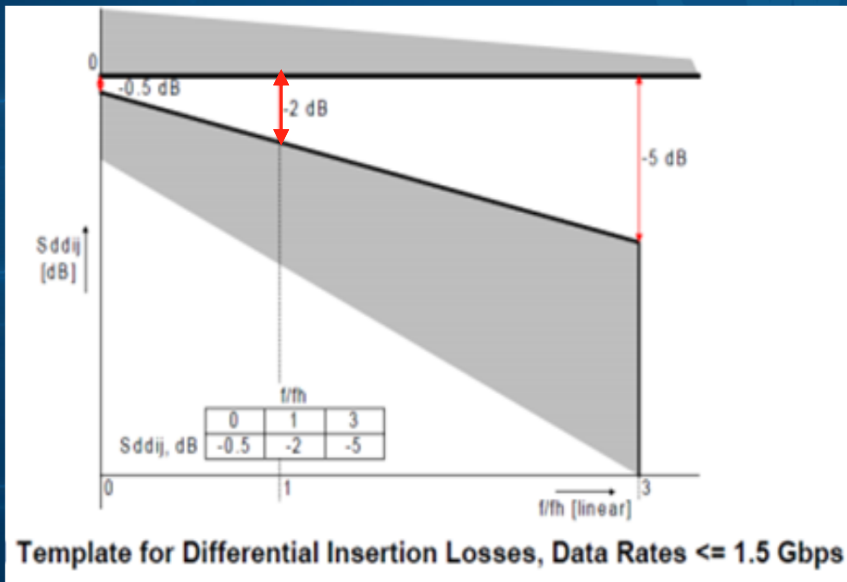
+



= 3Gbps

Interconnection Loss Specification in D-PHY

- Data rate $\leq 1.5\text{Gbps}$, loss requirement is less than -2db
- Data rate $> 1.5\text{Gbps}$, loss requirement is less than -3.75db

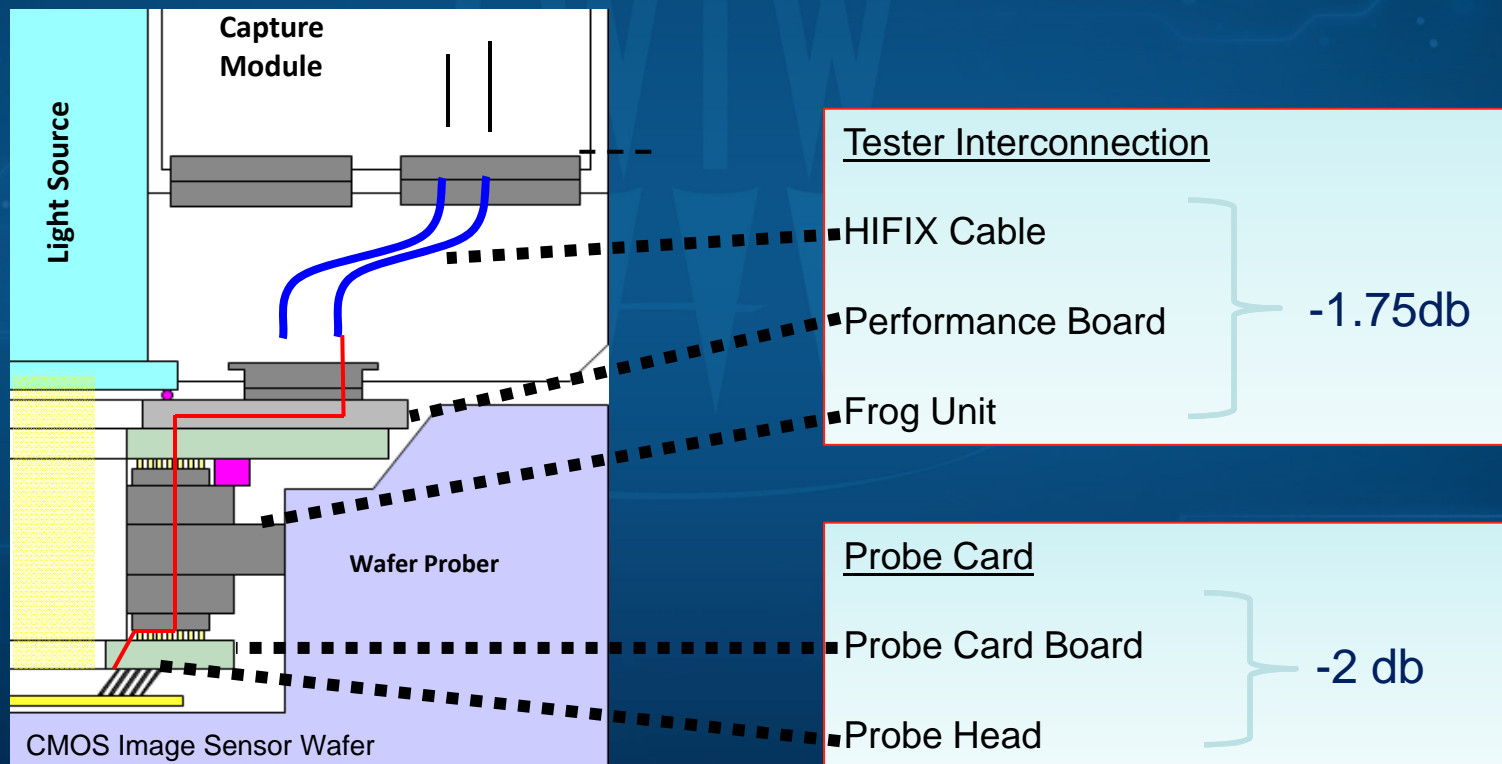


- Goals: Tester side -1.75db , Probe Card -2db , Total -3.75db loss with 50 Ohm impedance

* $f_h = \text{Data Rate}/2$

Tester Interconnection and Probe Card Goals

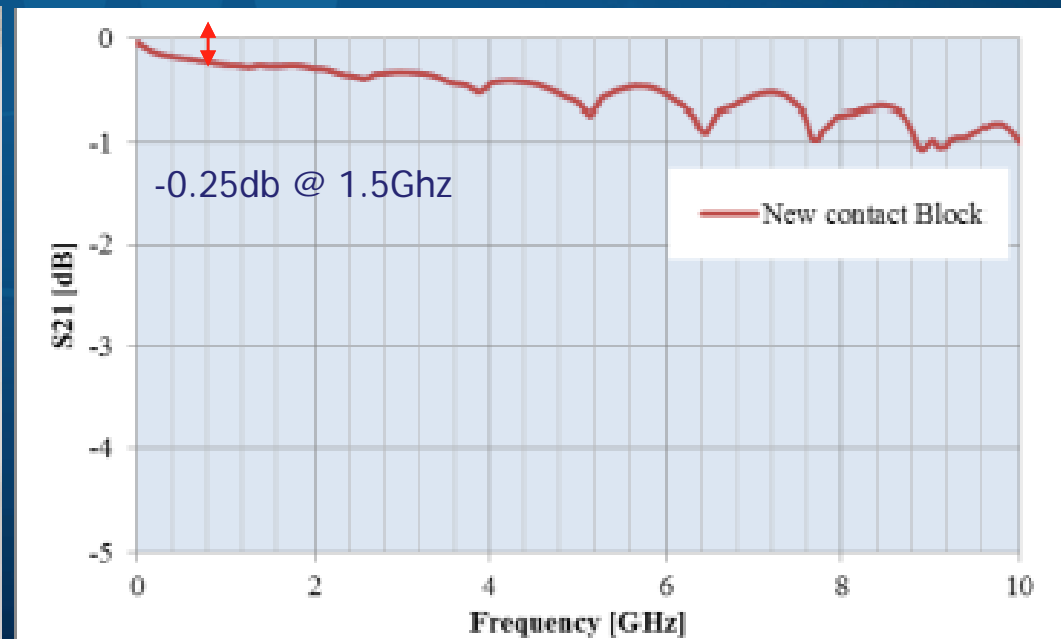
- 3.75db budget allocates -1.75db to tester, -2db to Probe Card



Tester Interconnection loss--Action and Results

- HIFIX Cable: Apply Wide Band Width Cable & Connector
- Performance Board: Apply design rule for high speed transmission line
- Frog Unit: Improve characteristic over 6Gbps (-0.25db)

2048ch Frog Unit (characteristic (S21))



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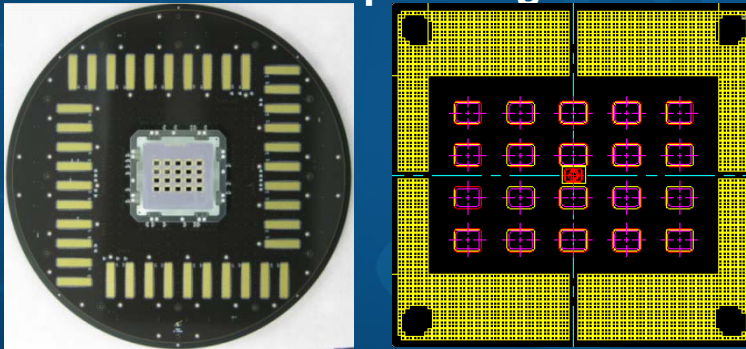
Figure above shows characteristic of BLOCK itself. Condition : Std Docking Stroke (2.0mm) under 25degree.

15

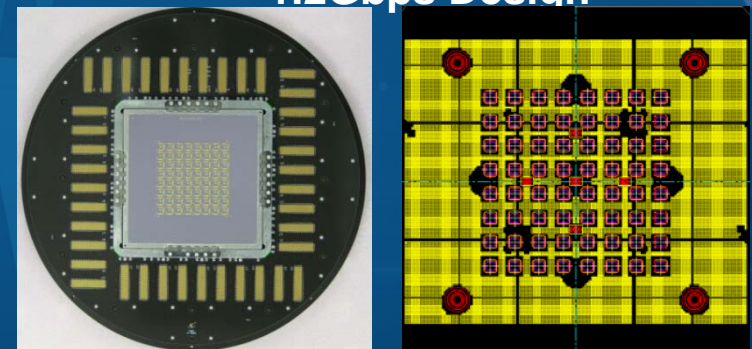
Probe Card Loss--- Phase 1 Action and Results

- Design Method PH: LGA between the DUT, MIPI differential pair trace length shortened
- Design Rule All: HFTAP high speed transmission line design rule

800Mbps Design



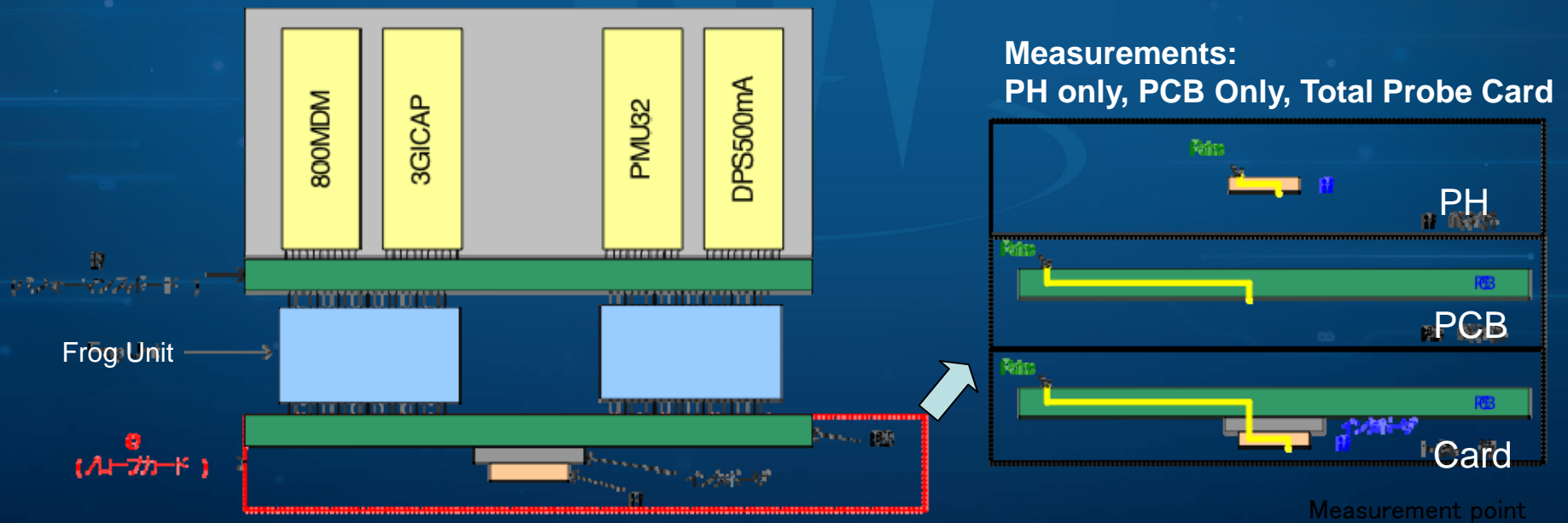
1.2Gbps Design



	800Mbps Design	1.2Gbps Design
Parallelism	20	64
Probe Head	-1.12 to -0.72 (dB)	-0.67 to -0.49 (dB)
PCB	-3.4dB	-2.3dB
<u>Total Probe Card Loss</u>	<u>-4db</u>	<u>-3db</u>

Probe card loss ---Phase 2 Action and measurement plan

- Design Method PH: More LGA between the DUT, MIPI differential pair trace
- PCB: Trace improvement for differential pair, and back drilling
- Design Rule All: New HFTAP high speed transmission line design rule



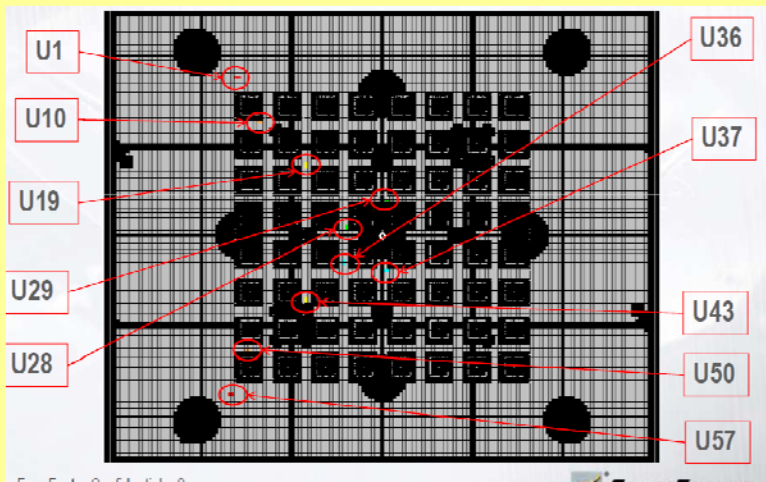
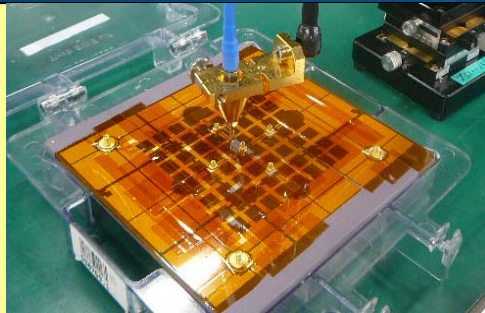
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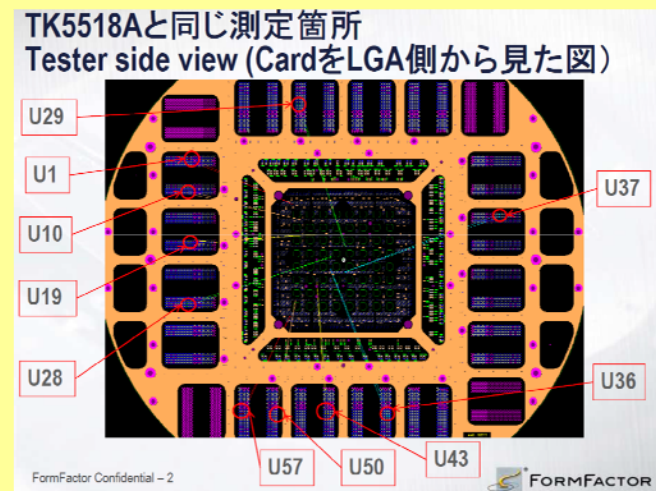
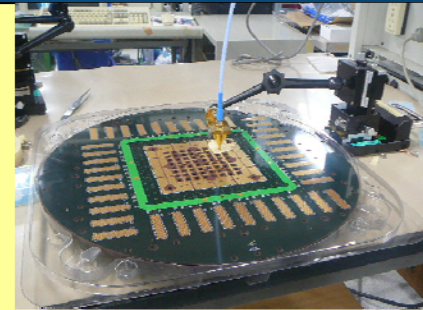
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Measurement Method and Points

- Measurement: Open ended rise time measurement by TDR 20-80%, 10 measurement points



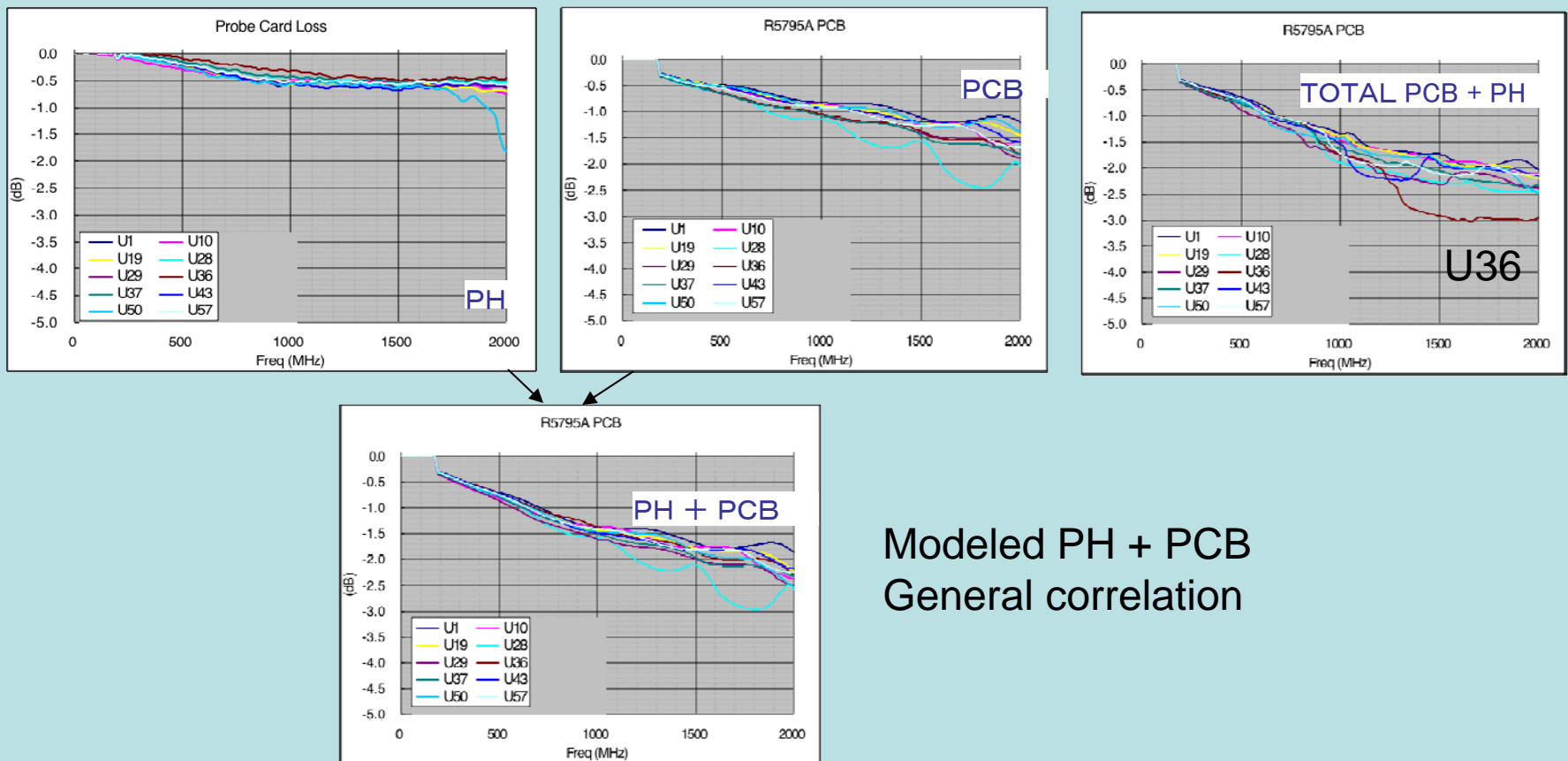
Probe Head Only



Probe card (PH+PCB)

Probe Card Loss Phase 2 Result S21

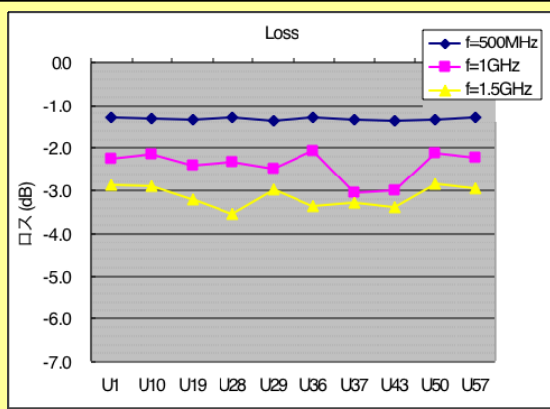
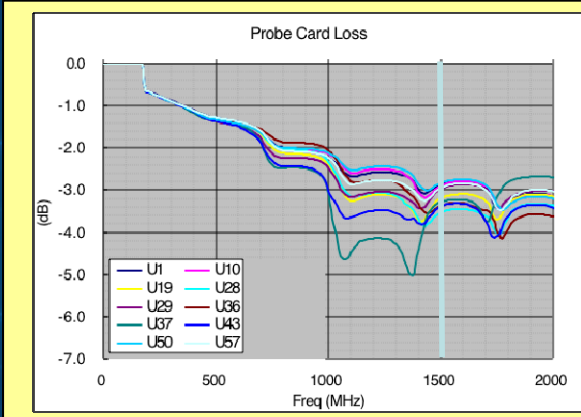
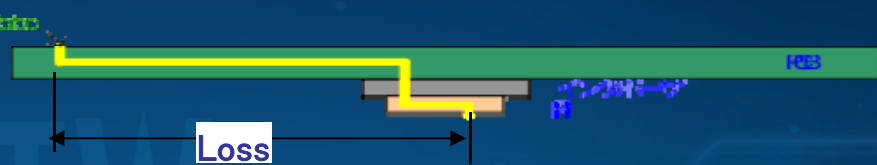
- Well correlated “Probe head only and PCB” and “Total Probe card” loss (Except U36 measurement error)



Modeled PH + PCB
General correlation

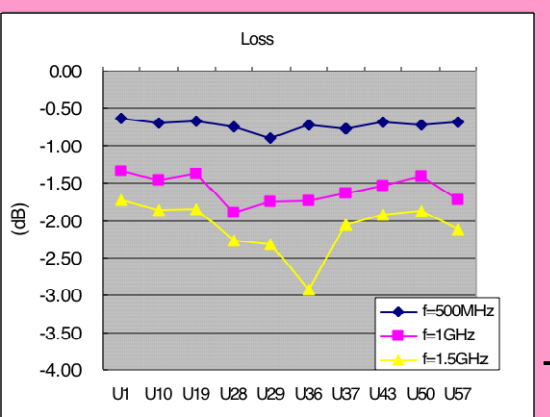
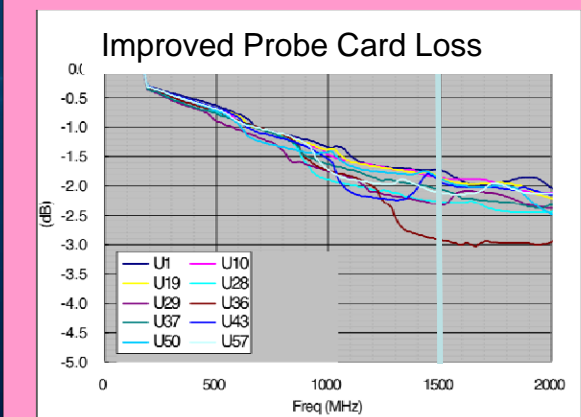
Probe Card Loss Phase 2 Result S21

- Loss improved 0.6 to 1.1db



1.2Gbos design

-2.84dB to -2.95dB (Except U36)

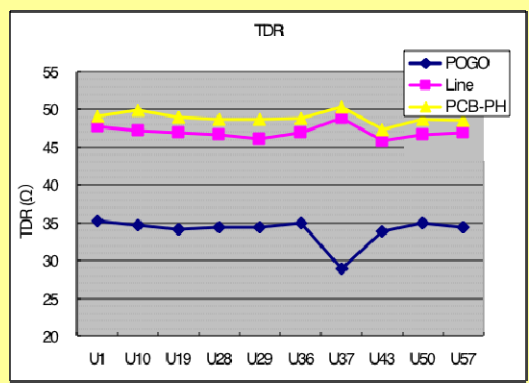
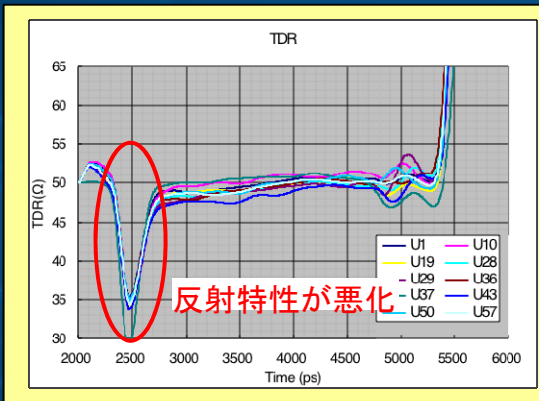


3Gbps Design

Target 2dB
-1.72 to 2.32dB (Except U36)

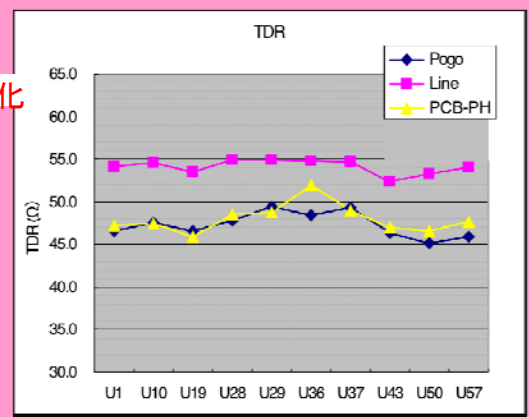
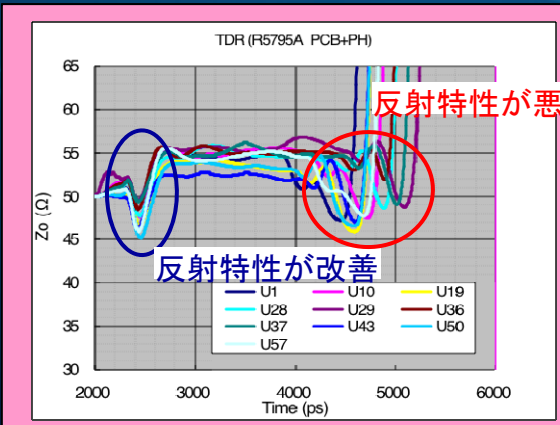
Probe Card Loss Phase 2 Result TDR

- Reduced impedance tolerance, less reflection



1.2Gbps Design

Pogo : 29.0 Ω ~ 35.3 Ω
 Line : 45.8 Ω ~ 48.8 Ω
 PCB-PH : 47.4 Ω ~ 50.3 Ω (MIN)
 50.5 Ω ~ 53.5 Ω (MAX)



3Gbps Design

Pogo : 45.2 Ω ~ 49.4 Ω
 Line : 52.4 Ω ~ 54.9 Ω
 PCB-PH : 45.9 ~ 51.9 Ω (MIN)

Probe Card Loss Phase 2 Results Summary

Loss @ F=1.5Ghz	Typical Design Rules (ie ≤ 1.2 Gbps)	3Gbps Design Rules
Parallelism	64	64
Total Probe Card S21 Loss	-3db*	1.72 to 2.32dB
3Gbps S21 Loss Goal	-2db	
Judgment	Fail*	Acceptable with minor adjustments
Total Probe Card Impedance @ Tr100ps		Pogo: 45.2 to 49.4 Ω PCB: 45.9 to 51.9 Ω
3Gbps S21 Loss Goal	47-53 Ω	
Judgment	Fail*	Acceptable

*Prevailing design rules found not to be sufficient to achieve higher speeds

Follow On Works

- **Light source keep-out area on PCB reduction by developing LED light source**
- **Advanced Probe Card Material and design rule implementation**